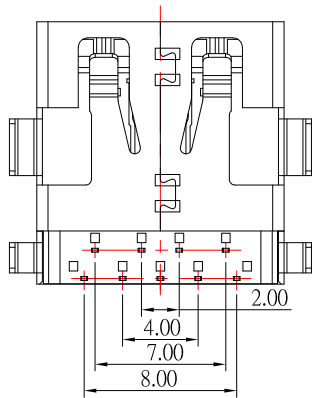
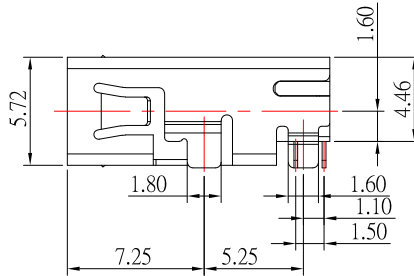
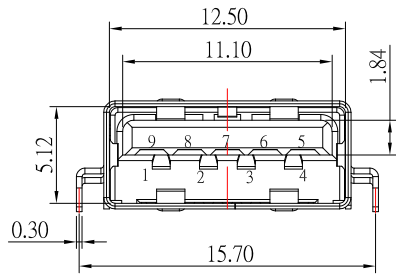
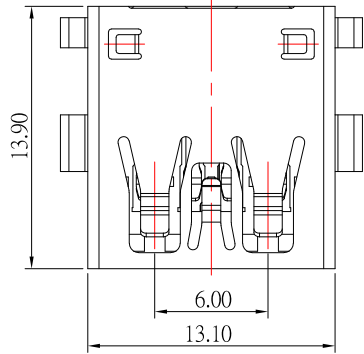




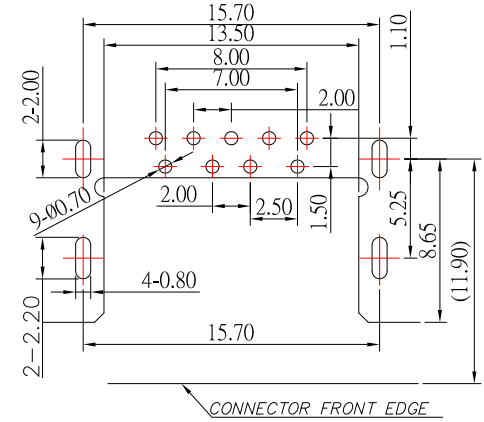
SUA-110E8-30x-S242

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"



Pin #	SIGNAL NAME
1	VBUS
2	D-
3	D+
4	GND
5	StdA_SSRX-
6	StdA_SSRX+
7	GND_DRAIN
8	StdA_SSTX-
9	StdA_SSTX+
Shell	Shield



PCB LAYOUT

NOTE:

1.MATERIAL:

- 1.1 Housing: LCP
- 1.2 Contact: Phosphor Bronze
- 1.3 Shell: SUS

2.Finish:

- 2.1 Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall
- 2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

- 3.1 Current Rate: 1.5 A
- 3.2 insulator Resistance: 100MΩ Min
- 3.3 Dielectric Strength: 500V AC
- 3.4 Contact Resistance: 30mΩ Max
- 3.5 Insertion Force: 35 N
- 3.6 Extraction Force: 10 N



TOLERANCE UNLESS OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD. ANGEL'S



UNITS

MM

DRAWN BY:	DATE
Jack Lu	08/13/24
CHECKED BY:	DATE
Jacky Chen	08/13/24
APPROVED BY:	DATE
Tony Kao	08/13/24

MATL	TITLE	CONNECTOR
FINISH	MODLE	USB 3.0 A/F 沉板H:4.46 DIP, 無捲邊
SCALE	DWG NO.	SUA-110E8-30x-S242
SHEET NO.	PART NO.	SUA-110E8-30x-S242
	SIZE	A4
	VER	R1

1	更新圖面	Jack	081324
ITEM NO.	DESCRIPTION	DRAWN	DATE